ASSOCIATION CONNECTING ALLCTRONICS INDUSTRIES International and F	position De IPC, Bannockt an-American co	c laration ourn, Illinois. A opyright conver	All rights reserved untions.	under both	This docume level parts, t	ent is a declaration he declaration en	on of the substand ncompasses all lo	es within the manufac wer level materials for	turer listed which the	item. Note: if manufacturer	the item is an as has engineering	ssembly with low responsibility.
	IPC Web Site for Information on IPC-1752 Standard Form Typ			*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information							
upplier Information												
Company name* Company unique II			ique ID		Unique ID Authority			Response Date*				
onsemi									2023-0	6-08		
Contact Name Title - Contact			ct]	Phone - Contact* En				Email - Contact*		
Product-Env-Stewards Prod			Product Enviro Compliance			NA			Produ	Product-Env-Stewards@onsemi.com		
Authorized Representative* Title - Represent			sentative	Phone - Representative* Email - Representative*								
Product-Env-Stewards Product I			ro Compliance		NA Product-Env-Stewards@onsemi.com					m		
Requester Item Number			Number Mfr Item Name			Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type
	STK531	U369C-E	Inverter			2023-06-08		VN2		14100.0	mg	Each
Ianufacturing Proccess Inform	ation						-				-	·
Terminal Plating / Grid Array Material Terminal Base A		Alloy	J-STD-020 MSI	L Rating	Peak Proce	ess Body Tempera	ture Max Time at Pe	ak Temper	ature Numb	er of Reflow Cyc	cles	
Matte Tin (Sn) - annealed CU Alloy			NA		0	С	30	seco	onds 3			
omments												
or more information regarding materi	al composition	please refer to	page 3									

RoHS Material Composition Declaration				Declaration Type *	Detailed			
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-ethers)				
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexcess encompass all such components.Supplier cert as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided certification in this paragraph.If the Company	ted biphenyls and/or polybrominated dip of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ve relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr source of the Supplier's liability and the	henyl ethers (each a "RoHS restricted subs ndicate below which, if any, RoHS exempt ovides in this form using appropriate meth will rely on this certification in determinin ers in completing this form, and that Suppl num, itssuppliers have provided certificatio eement with respect to the identified part,t Company's remedies for issues that arise r	stance") in exce ion you believe ods to ensure i g the compliar ier may not ha ons regarding t he terms and co	ropean Union member states) of the part identifiess of the applicable quantity limit identified able may apply. If the part is an assembly with low is accuracy and that such information is true and ce of its products with European Union member independently verified such information. How heir contributions to the part, and those certifica onditions of that agreement, including any warra nation the Supplier provides in this form. In the	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the inty rights and/or remedies provided as part of			
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for se	elected exempt	ions Supplier Acceptance	* Accepted			
Exemption: 7c-I Electrical and electronic c	omponents containing lead in a glass o	r ceramic other than dielectric ceramic	in capacitors,	e.g. piezoelectronic devices, or in a glass or c	eramic matrix compound.			
Exemption List Version	EL-2011/534/EU							
Declaration Signature								
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.								
Supplier Digital Signature R	astislav Drska	Le						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Ceramic Substrate	3930.48	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		49.131	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		193.7727	mg
			В	Nickel (Ni)	7440-02-0		6.6818	mg
			Supplier	Acrylic resins	Proprietary Data		2.7513	mg
			Supplier	Copper (Cu)	7440-50-8		264.1282	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		1.9652	mg
			Supplier	Aluminum (Al)	7429-90-5		3412.0496	mg
hip Parts	45.36	mg	Supplier	Silver (Ag)	7440-22-4		1.2338	mg
-			Supplier	Epoxy resins	129915-35-1		0.4355	mg
			Supplier	Tin (Sn)	7440-31-5		1.3427	mg
			Supplier	Magnesium Monoxide (MgO)	1309-48-4		0.0635	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.7802	mg
			Supplier	Ceramic	12013-47-7, 12047- 27-7		8.4642	mg
			Supplier	Phenolic resins	Proprietary Data		0.0544	mg
			Supplier	Palladium (Pd)	7440-05-3		0.0045	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		27.7104	mg
			В	Nickel (Ni)	7440-02-0		2.2272	mg
			А	Lead Oxide (PbO)	1317-36-8	7c	0.0635	mg
			Supplier	Copper (Cu)	7440-50-8		2.6762	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.3039	mg
vie	30.06	mg	Supplier	Silicon (Si)	7440-21-3		30.06	mg
vie Attach	1.62	mg	Supplier	Silver (Ag)	7440-22-4		1.1034	mg
			Supplier	Other Epoxy resins	Proprietary Data		0.2435	mg
			Supplier	Tin (Sn)	7440-31-5		0.1714	mg
			Supplier	Other Metal Oxide	Proprietary Data		0.0616	mg
			В	Antimony (Sb)	7440-36-0		0.0159	mg
			В	Antimony Pentoxide (Sb2O5)	1314-60-9		0.0243	mg
Heat Sink	869.5	mg	Supplier	Silver (Ag)	7440-22-4		139.12	mg
			Supplier	Copper (Cu)	7440-50-8		730.38	mg
ead Frame	527.07	mg	Supplier	Tin (Sn)	7440-31-5		0.3162	mg
			Supplier	Copper (Cu)	7440-50-8		526.7538	mg

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Mold Compound-Black	8586.38	mg		Brominated epoxy resin	proprietary data	18.89	mg
			Supplier	Phenolic Resin	Proprietary Data	443.0572	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4	13.7382	mg
			Supplier	Carbon Black (C)	1333-86-4	35.2042	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2	609.633	mg
			Supplier	Fused Silica (SiO2)	60676-86-0	5712.5186	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2	944.5018	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7	808.837	mg
Plating	1.05	mg	Supplier	Tin (Sn)	7440-31-5	0.6501	mg
			В	Nickel (Ni)	7440-02-0	0.3999	mg
Solder Ball	19.87	mg	Supplier	Silver (Ag)	7440-22-4	0.5544	mg
			Supplier	Tin (Sn)	7440-31-5	19.2024	mg
			В	Antimony (Sb)	7440-36-0	0.0159	mg
			Supplier	Copper (Cu)	7440-50-8	0.0974	mg
Wire Bond - Al	88.61	mg	Supplier	Aluminum (Al)	7429-90-5	88.61	mg